

Electronic Patent Application Fee Transmittal

Application Number:	10613326			
Filing Date:	03-Jul-2003			
Title of Invention:	Vertical conduction flip-chip device with bump contacts on single surface			
First Named Inventor/Applicant Name:	Daniel M. Kinzer			
Filer:	Kourosh Salehi/Gloria Levy			
Attorney Docket Number:	IR-2541 DIV			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	1401	1	540	540
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				540